STTH602C-Y



Automotive ultrafast recovery diode

Datasheet - production data

Features

- Suited for SMPS
- Low losses
- Low forward and reverse recovery time
- High surge current capability
- High junction temperature

Description

This dual center tap diode is suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in DPAK, this device is intended for use in low voltage high frequency inverters, free wheeling and polarity protection for automotive applications.

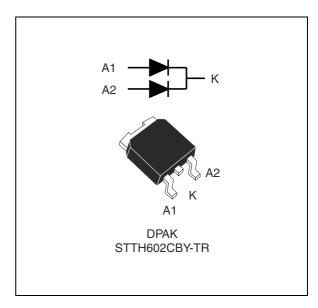


Table 1. Device summary

I _{F(AV)}	2 x 3 A
V_{RRM}	200 V
T _j (max)	175° C
V _F (typ)	0.80 V
t _{rr} (typ)	14 ns

Characteristics STTH602C-Y

1 Characteristics

Table 2. Absolute ratings (limiting values at $T_i = 25^{\circ}$ C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			200	V
I _{F(RMS)}	RMS forward current	RMS forward current			Α
1	Average forward current, $\delta = 0.5$		Per diode T _c = 160° C	3	Α
I _{F(AV)}			Per device T _c = 155° C	6	A
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms Sinusoidal}$		60	Α	
T _{stg}	Storage temperature range			-65 to + 175	° C
T _j	Operating junction temperature			-40 to + 175	° C

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit	
В	lunation to appe	Per diode	5	° CAM
R _{th(j-c)}	Junction to case	Per device	3.0	
R _{th(c)}	Coupling	Per diode	1	° C/W
	Coupling	Per diode	3	

When the two diodes 1 and 2 are used simultaneously:

 $\Delta Tj(diode\ 1) = P\ (diode\ 1)\ X\ R_{th(j\text{-}c)}\ (Per\ diode) + P\ (diode\ 2)\ x\ R_{th(c)}$

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25° C	V V		3	μΑ
'R`	IR Prevense leakage current	T _j = 125° C	$V_R = V_{RRM}$	3	30	
		T _j = 25° C	1 2 4	0.98	1.1	
V _F ⁽²⁾	Forward voltage drop	$T_j = 150^{\circ} \text{ C}$ $I_F = 3 \text{ A}$	8.0	0.95	V	
v F, ,	V _F ····································	T _j = 25° C		1.1	1.25	V
		T _j = 150° C	I _F = 6 A	0.9	1.05	

^{1.} Pulse test: $t_p = 5$ ms, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.85 \text{ x } I_{F(AV)} + 0.033 I_{F}^{2}_{(RMS)}$$

^{2.} Pulse test: t_p = 380 μ s, δ < 2%

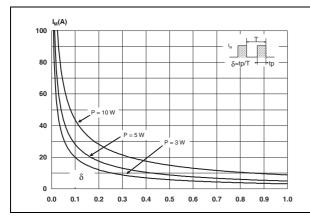
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Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
+	Reverse recovery time	$I_F = 1 \text{ A, } dI_F/dt = -100 \text{ A/}\mu\text{s,}$ $V_R = 30 \text{ V, } T_j = 25 \text{ °C}$		14	20	ns
t _{rr}	neverse recovery unite	$I_F = 1 \text{ A, } dI_F/dt = -50 \text{ A/}\mu\text{s,}$ $V_R = 30 \text{ V, } T_j = 25 \text{ °C}$		21	30	
I _{RM}	Reverse recovery current	$I_F = 3 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 160 \text{ V}, T_j = 125 ^{\circ}\text{C}$		4	5.5	Α
t _{fr}	Forward recovery time	$I_F = 3 \text{ A, } dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_{FR} = 1.1 \text{ x } V_{Fmax}, T_j = 25 \text{ °C}$		24		ns
V _{FP}	Forward recovery voltage	$I_F = 3 \text{ A, } dI_F/dt = 200 \text{ A/}\mu\text{s,}$ $T_j = 25 ^{\circ}\text{C}$		3.7		٧

Figure 1. Peak current versus duty cycle (per diode)

Figure 2. Forward voltage drop versus forward current (typical values per diode)



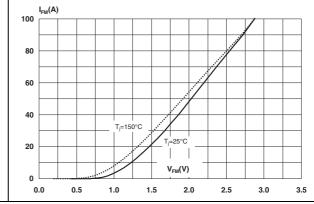
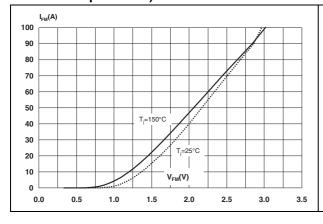
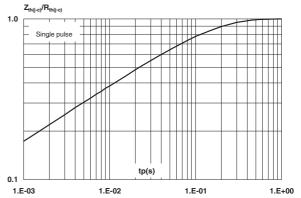


Figure 3. Forward voltage drop versus forward current (maximum values per diode)

Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

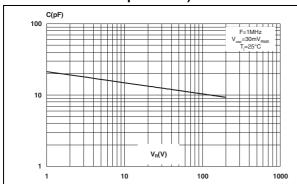




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Figure 5. Junction capacitance versus reverse applied voltage (typical values per diode)

Figure 6. Reverse recovery charges versus dl_F/dt (typical values)



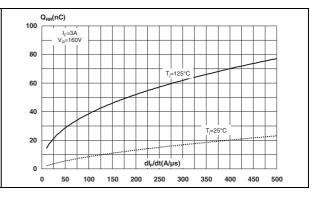
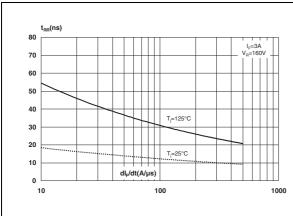


Figure 7. Reverse recovery time versus dl_F/dt Figure 8. Peak reverse recovery current (typical values)



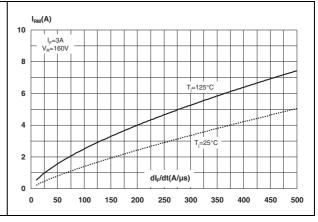
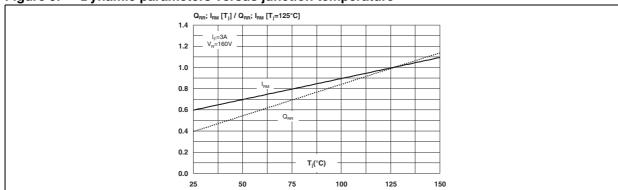


Figure 9. Dynamic parameters versus junction temperature



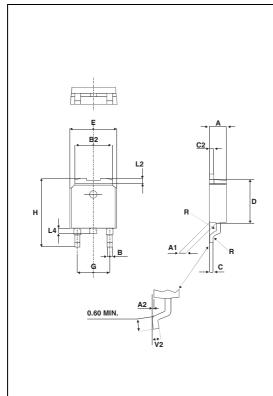
STTH602C-Y Package information

2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

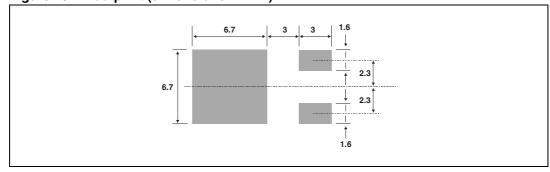
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Table 6. DPAK dimensions



	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α	2.20	2.40	0.086	0.094	
A1	0.90	1.10	0.035	0.043	
A2	0.03	0.23	0.001	0.009	
В	0.64	0.90	0.025	0.035	
B2	5.20	5.40	0.204	0.212	
С	0.45	0.60	0.017	0.023	
C2	0.48	0.60	0.018	0.023	
D	6.00	6.20	0.236	0.244	
Е	6.40	6.60	0.251	0.259	
G	4.40	4.60	0.173	0.181	
Н	9.35	10.10	0.368	0.397	
L2	0.80 typ.		0.03	1 typ.	
L4	0.60	1.00	0.023	0.039	
V2	0°	8°	0°	8°	

Figure 10. Footprint (dimensions in mm)



Ordering information STTH602C-Y

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH602CBY-TR	STTH602CBY	DPAK	0.30 g	2500	Tape and Reel

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
24-Oct-2012	1	First issue.

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